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José Epifânio Da Franca

Universidade de Lisboa, Portugal

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Date: Tuesday, September 12, 2023
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Muriel Médard

Massachusetts Institute of Technology, United States

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Princeton University, United States

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[1]Princeton University, United States; [2]Ain Shams University, Egypt;
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[1]Fraunhofer Institute for Electronic Microsystems and Solid State Technologies EMFT, Germany;
[2]Technische Universität München, Germany

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Date: Tuesday, September 12, 2023
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Barbara de Salvo

META Reality Labs Research, United States

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Room: Audit. III
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Date: Tuesday, September 12, 2023
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[1]Fondazione Bruno Kessler, Italy; [2]University of Trento, Italy

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[1]Ajou University, Korea; [2]Arizona State University, United States; [3]Chosun University, Korea

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Monolithic Power Systems, Inc., United States

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[1]Hong Kong University of Science and Technology, Hong Kong; [2]AI Chip Center for Emerging Smart Systems, Hong Kong; [3]Westlake University, China

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[1]University of Texas at Austin, United States; [2]North Carolina State University, United States

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[1]Georgia Institute of Technology, United States; [2]Kennesaw State University, United States

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[1]Korea Advanced Institute of Science and Technology, Korea;
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[1]National Yang Ming Chiao Tung University, Taiwan; [2]National Taiwan University, Taiwan

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Date: Thursday, September 14, 2023
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[1]Axelera AI, Belgium; [2]IMEC, Belgium; [3]Katholieke Universiteit Leuven, Belgium

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[1]Columbia University, United States; [2]Intel Corporation, United States

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University of Texas at Dallas, United States

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[1]Korea University, Korea; [2]Korea Electronics Technology Institute, Korea

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[1]University of California, Berkeley, United States; [2]Boston University, United States

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Jaekyum Lee[1], Albert Theuwissen[1,2]

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Chair(s): Susanna Reggiani, *University of Bologna*
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